

GCT's Single Chip Advantage: RF + Baseband on a Single Chip

Features

- Cat4 LTE 150 Mbps downlink, 50 Mbps uplink
- 3GPP Release 9
- On-Chip VoLTE, eMBMS
- TDD and FDD: Supports all frequency bands
- IMS, OTA-DM, etc. integrated
- Seamless handover between FDD and TDD-LTE
- Hostless stand-alone (CPE, USB Dongle, M2M)
- Complete LTE protocol stack and host software
- Global LTE roaming (multi-band support: >8 bands simultaneously)

Interfaces

- USB2 (Device & Host)
- SDIO 3 (Device & Host)
- HSI
- SPI
- E-MEM
- R-GMII
- I2S
- PCM
- NAND
- UART
- GPIO
- SIM

Package Outline

- 12x12x1.2 mm BGA package
- Integrated memory optional



Key Benefits

- Low Power Consumption
- High Integration (BB, RF), lower cost of ownership
- Turnkey VoLTE, eMBMS, etc.
- High Performance
- Inter and Intra-band Capability

Applications

- Smartphones, Tablets, etc.
- Mobile Hotspots, CPEs
- USB Dongles
- M2M Modules
- Ultra books, Chrome books
- Data cards

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